



VMDSEMI

**VUTL006R190NA**

**Datasheet**



VMDSEMI

## General Description

## Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
60V	19mΩ@10V	40A
	45mΩ@4.5V	

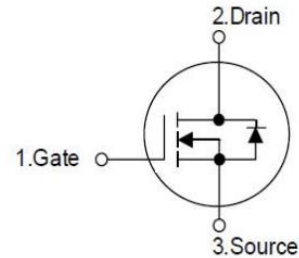


Figure 1 Symbol of VUTL006R190NA

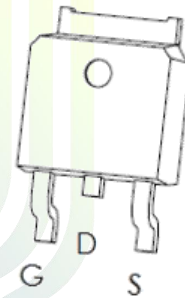
## Features

- Trench Technology Power MOSFET
- Low  $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested
- 100%  $\Delta V_{DS}$  Tested

## Application

- Power Switch Application

## Package Type



**TO-252-2L**

Figure 2 Package Type of VUTL006R190NA

## Ordering Information

Product Name	Package
VUTL006R190NA	TO-252-2L

**Absolute Maximum Ratings** ( $T_A = 25\text{ °C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	60	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current <sup>Note1</sup>	$I_D$	40	A
Pulsed Drain Current <sup>Note2</sup>	$I_{DM}$	160	
Avalanche Current <sup>Note3</sup>	$I_{AS}$	20	
Single Pulsed Avalanche Energy <sup>Note3</sup>	$E_{AS}$	100	mJ
Total Power Dissipation <sup>Note5</sup>	$P_D$	60	W
Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	-55 to 150	°C

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient <sup>Note6</sup>	$R_{\theta JA}$		50		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		2.1		°C/W



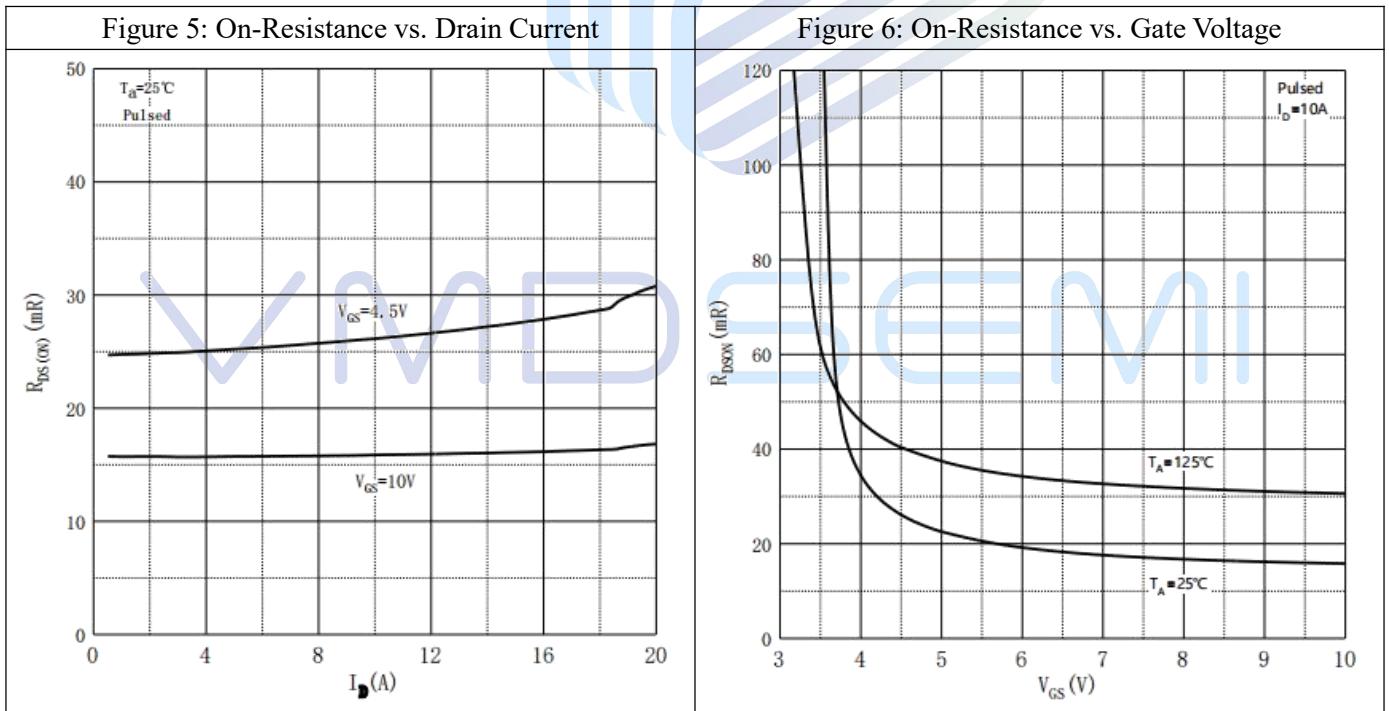
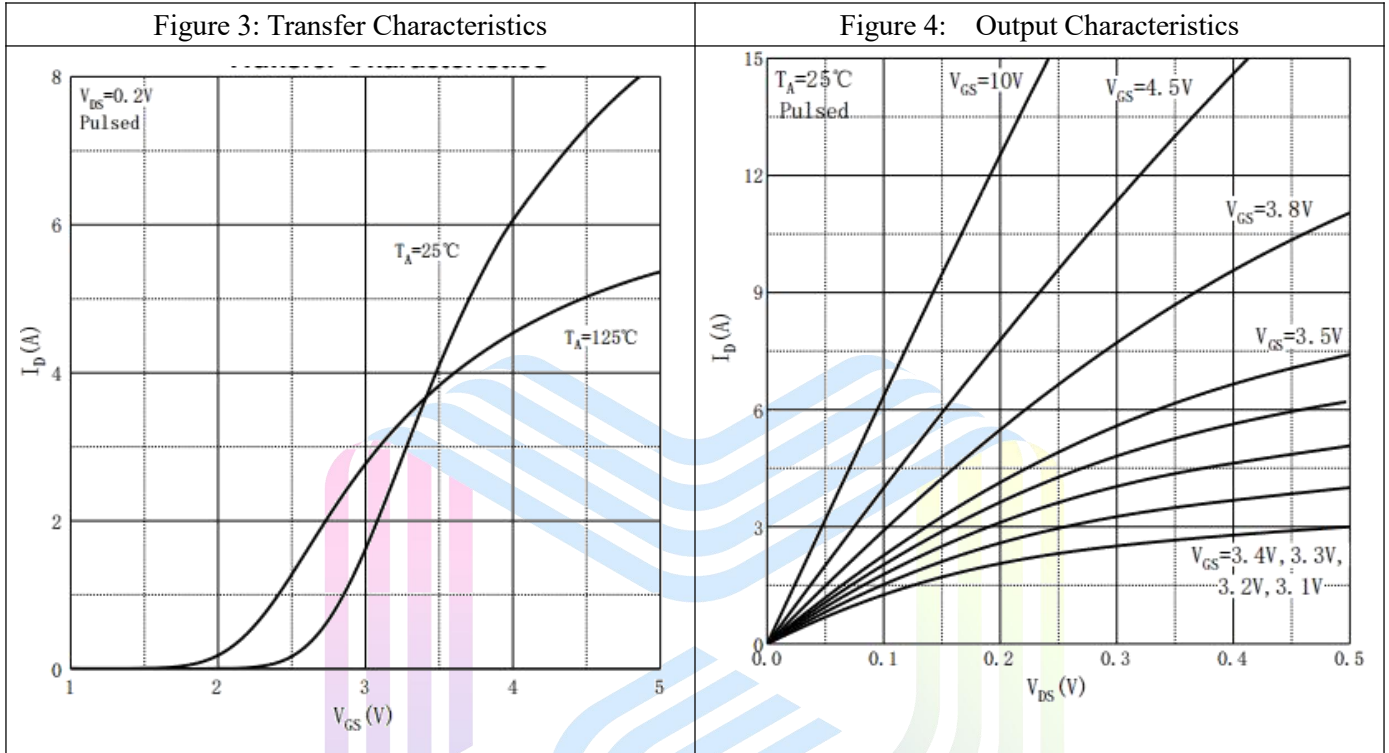
**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	60			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage <sup>Note4</sup>	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.7	3	V
Static Drain-Source On-Resistance <sup>Note4</sup>	$R_{DS(on)}$	$V_{GS}=10V, I_D=10A$		17	19	mΩ
		$V_{GS}=4.5V, I_D=10A$		26	45	
Forward Transconductance <sup>Note4</sup>	$g_{FS}$	$V_{DS}=5V, I_D=10A$	10			S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=30V$		1291		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		80		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$		75		pF
Total Gate Charge	$Q_g$	$V_{DS}=30V$		28.5		nC
Gate-Source Charge	$Q_{gs}$	$V_{GS}=10V$		7.6		
Gate-Drain Charge	$Q_{gd}$	$I_D=10A$		3.8		
Gate Resistance	$R_g$	$f=1MHz, \text{Open drain}$		1.28		Ω
<b>Switching Parameters</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=30V$		8		ns
Turn-on Rise Time	$t_r$	$V_{GS}=10V$		5		
Turn-off Delay Time	$t_{d(off)}$	$R_L=1.5\Omega$		30		
Turn-off Fall Time	$t_f$	$R_G=3\Omega$		5.5		
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>Note4</sup>	$V_{SD}$	$V_{GS}=0V, I_S=10A$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink.
- 2.Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3.EAS condition:  $V_{DD}=30V, V_{GS}=10V, L=0.5mH, R_G=25\Omega$  Starting  $T_J=25^\circ C$ .
- 4.Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 5.The power dissipation  $P_D$  is limited by  $T_{J(MAX)}=150^\circ C$ .And device mounted on a large heatsink
- 6.Device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ C$ .

### Typical Performance Characteristics



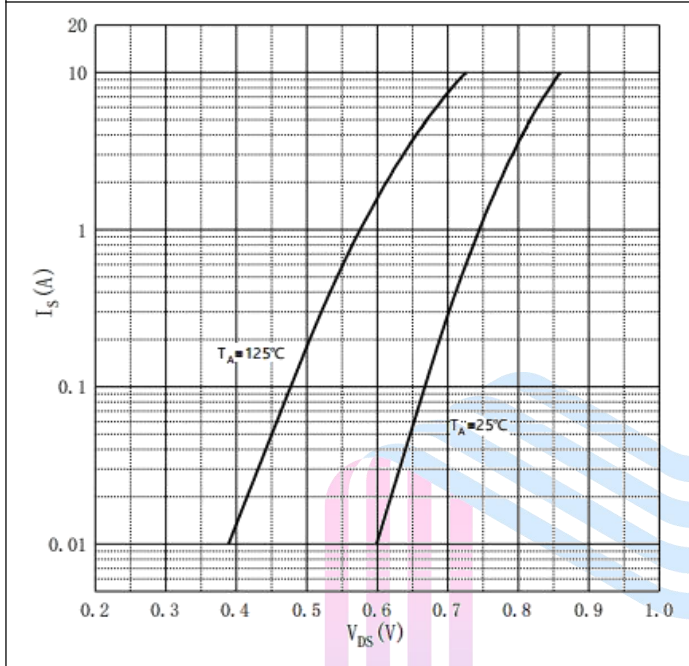
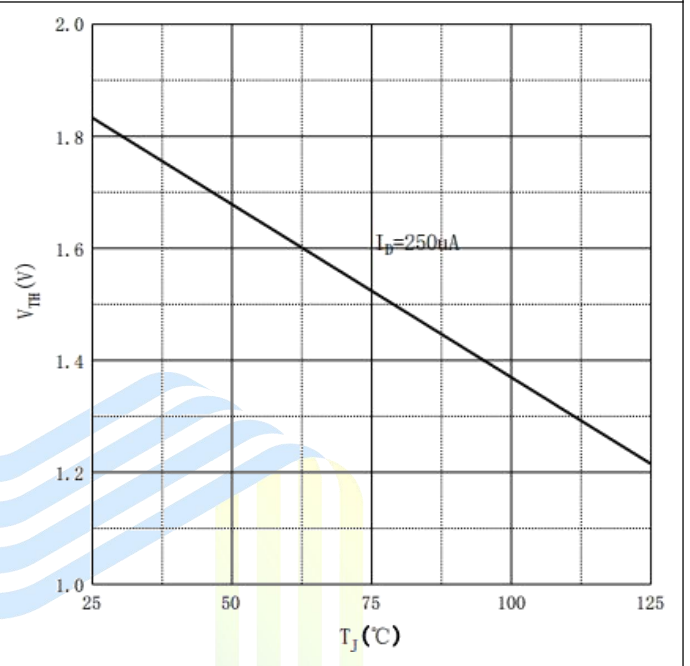
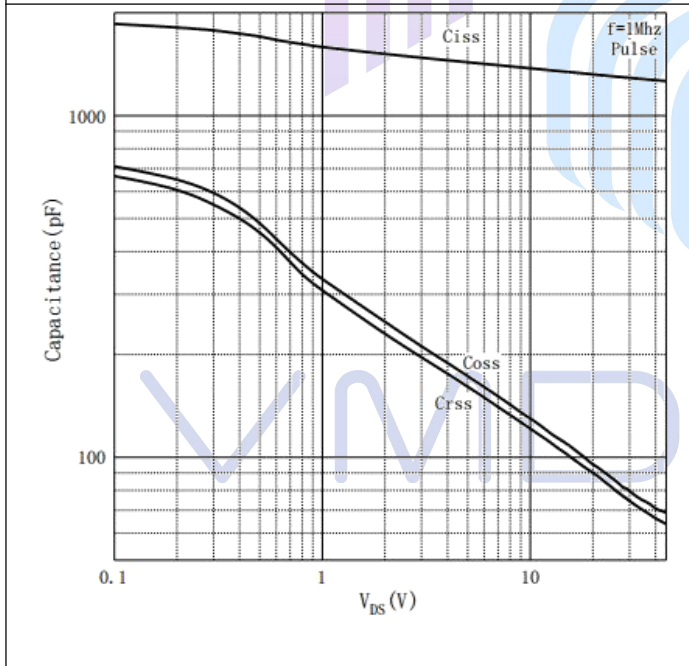
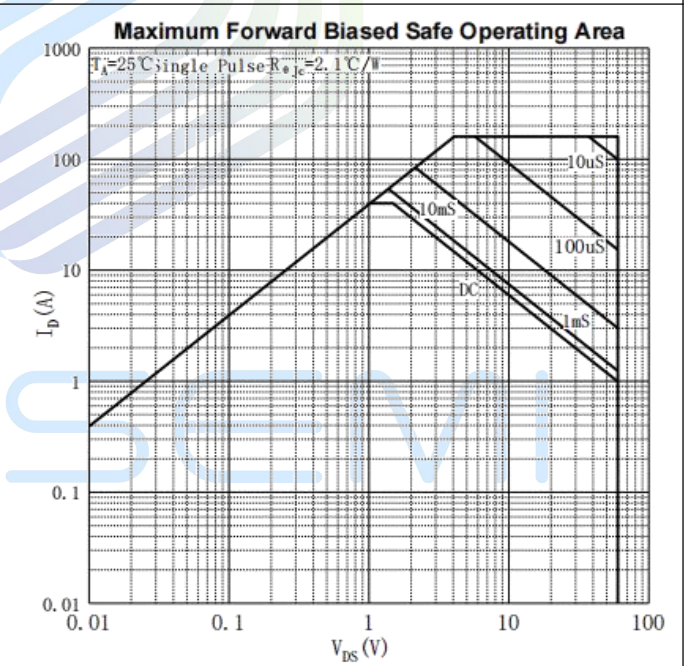
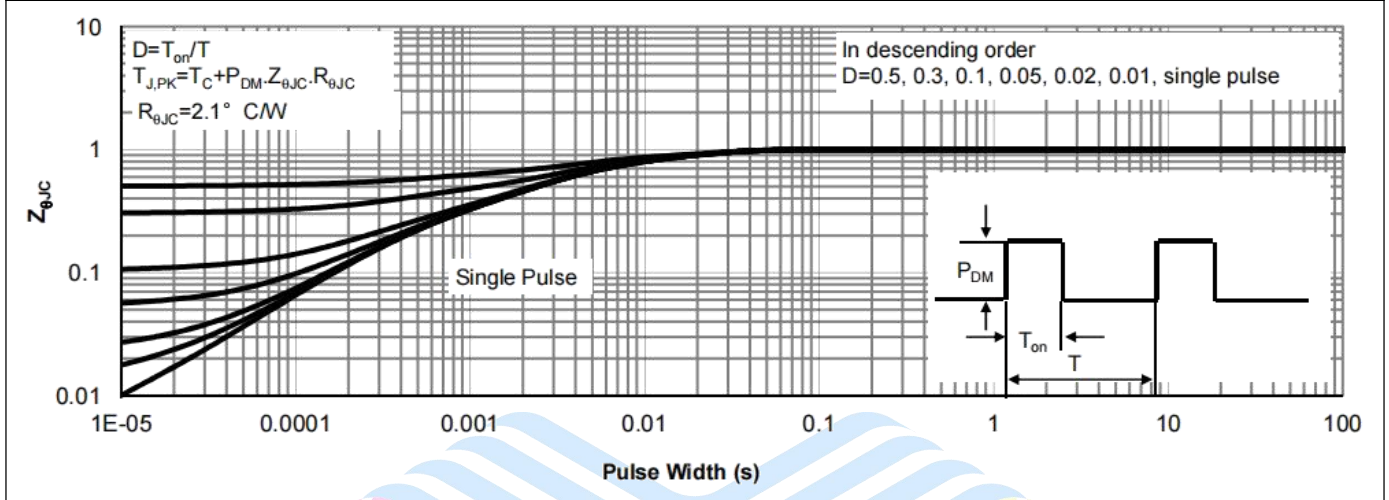
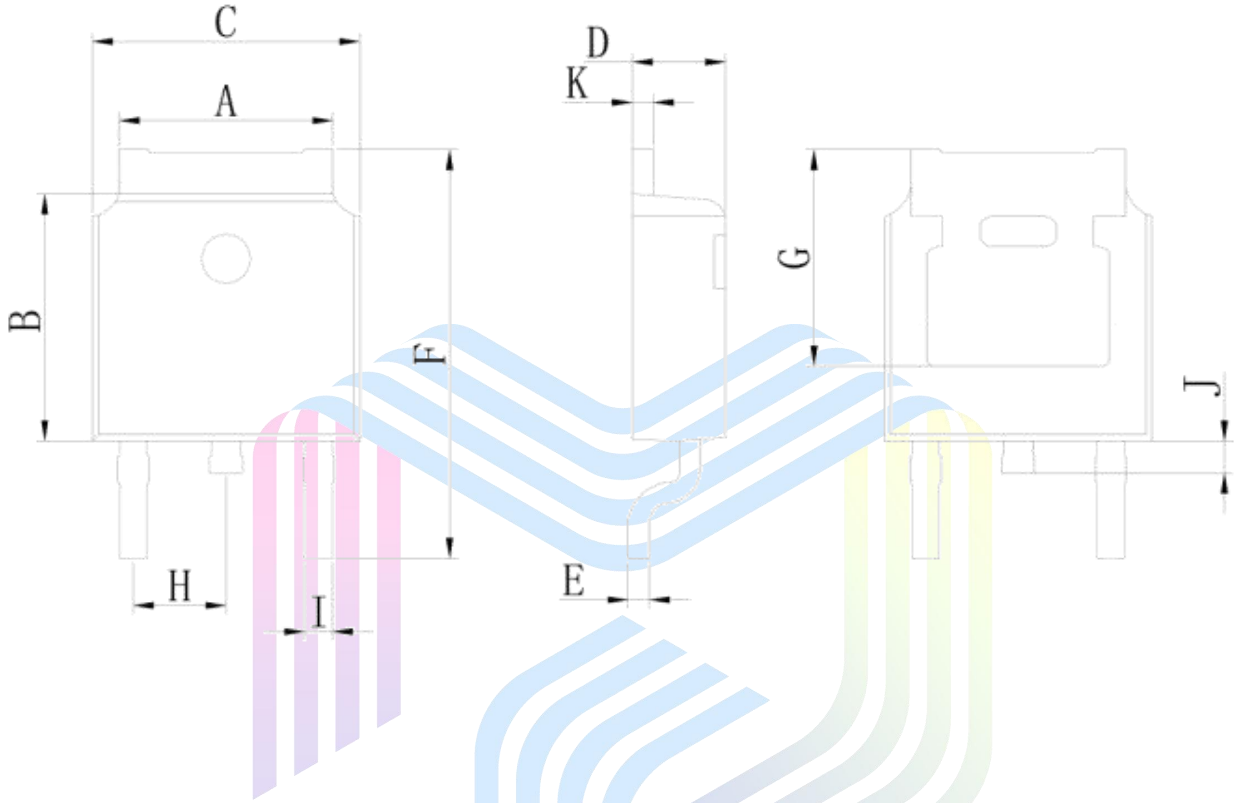
**Figure 7: Body Diode Characteristics**

**Figure 8: Threshold Voltage**

**Figure 9: Typical Capacitance**

**Figure 10: Safe Operation Area**


Figure 11: Normalized Maximum Transient Thermal Impedance




# VMDSEMI

**Mechanical Dimensions:**
**TO-252-2L Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	5.050	5.650	0.199	0.222
B	5.800	6.400	0.228	0.252
C	6.250	6.850	0.246	0.270
D	2.200	2.400	0.087	0.094
E	0.400	0.600	0.016	0.024
F	9.710	10.310	0.382	0.406
G	5.050	5.650	0.199	0.222
H	2.100	2.500	0.083	0.098
I	0.700	0.900	0.028	0.035
J	0.500	0.900	0.020	0.035
K	0.400	0.600	0.016	0.024



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